-Shenzhen Biqu Technology 3D Printer G0B1 Project

BIGTREETECH_CB1_V2.4_220826

SOC:_H616

DDR:_D2516ECMDXGJD

MCU:_STM32G0B1RCT6

MODULE:_TL8189FCB

DCDC:_AXP313A

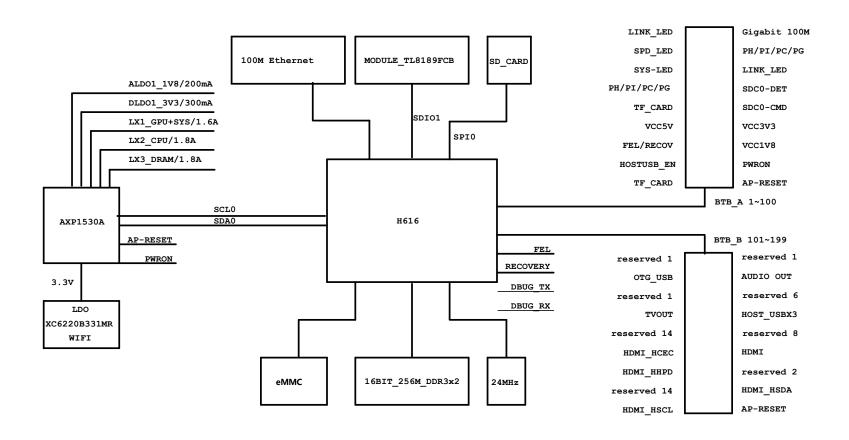
LDO: _RT9020-33GB

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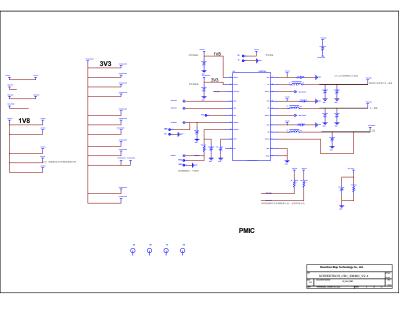


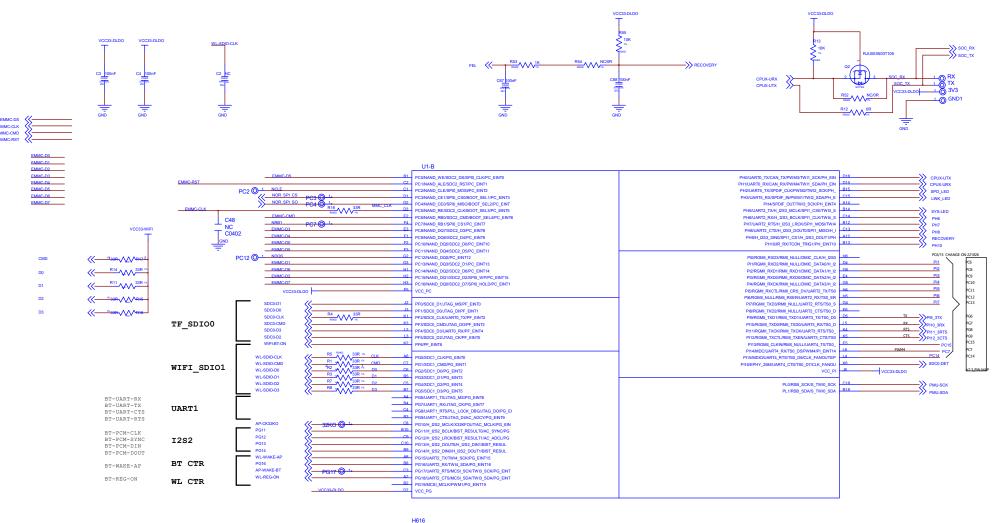
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Version history

Version	date	editor	Modify the description	approve
V01	2022.02.15	Byron Bai	1. 在全志H616原始设计上修改。 2. 取消EMMC,用NORFALSH启动,带TF卡。 3. WIFI改为模块TL8189FCB,不带蓝牙。 4. 增加两个BTB_DF40C-100DS-0-4V转接座子。	
CB1_V1.0	2022.04.12	Byron Bai	1.R43 要贴上,WIFI IO口用3.3V供电。取清榜R42, R43直连。 2.PC口 用1.8V.取清R40,3.3V的跳线; R41,1.8V跳线。 3.取清R44,用U5_RT9020-33GB直接供电给WIFI。 4.取消U7_MX25L12835FM2IU及相关器件。 5.取消 R56 R11 R35版本设置电阻 I K. 6.取消 RF6 R11 R35版本设置电阻 I K. 6.取消 WIFI 24 30PIN,取消WIFI 30P R51。 9.取消 R60 R61 LDO分性 10. SoCB15 C15 同口灯取消,用PHY上面的灯控制口。 11.自动选择不要了。 12.取消 A座 75P SD使能。 13.增加PHY RTL8211P和LDO供电。 14.修改更正SoC DDR IO的18.V使电。	
CB1_V2.0	2022.05.12	Byron Bai	1. 取消TF_CARD檢測 "PI14". 7.USB0 和USB1位置对调. 2. RGMII_MDC 由PI15更改到 PI14. 8.散热风扇控制更改为PC15. 3. RGMII_MDI0 由PI16更改到 PI15. 4. R53,R54,R55,C67,C68,C27,C22,R10 封装更改为0201. 5.取消测试应T13,T14,T15,T16,T28. 6.Y1 24MHz对装更改为2012.	
CB1_V2.1	2022.06.08	Byron Bai	1.取消PHY YT8531. 2.改回内置100M网.	
CB1_V2.2	2022.08.17	Byron Bai	1.PC IO口供电由1.8V变更为3.3V。	
CB1_V2.3	2022.08.26	Byron Bai	1.WIFI DO D1 D2 D3 SMD 增加信号33R,增加上拉30K,改善信号. 2.修改了WIFI模块的封装. 3.加粗了音频输出的宽度至8mi1. 4.U5_LDO RT9020-33GB 更换为XC6220B331MR-G,电流1A。	
CB1_V2.3	2022.10.25	WGZ	1.增加EMMC 2.优化部分走线 3.修改UART1到PIx_UART3	

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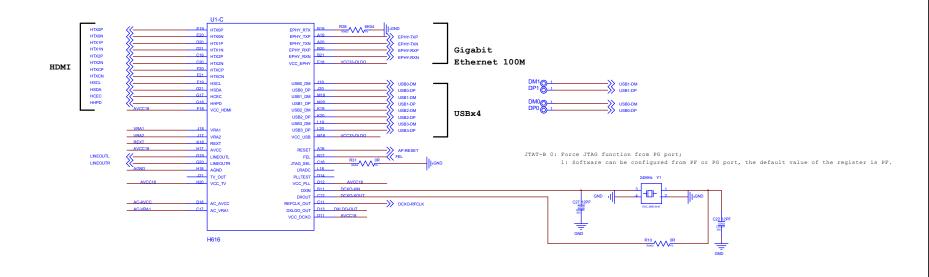


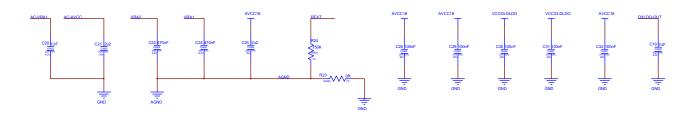
GPIO Instructions

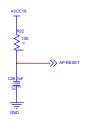
- 1. Note that the level of the SOC terminal matches the IO level of the peripheral
- 2. The IO pull-up voltage selects the voltage of the power domain to which the corresponding GPIO belongs



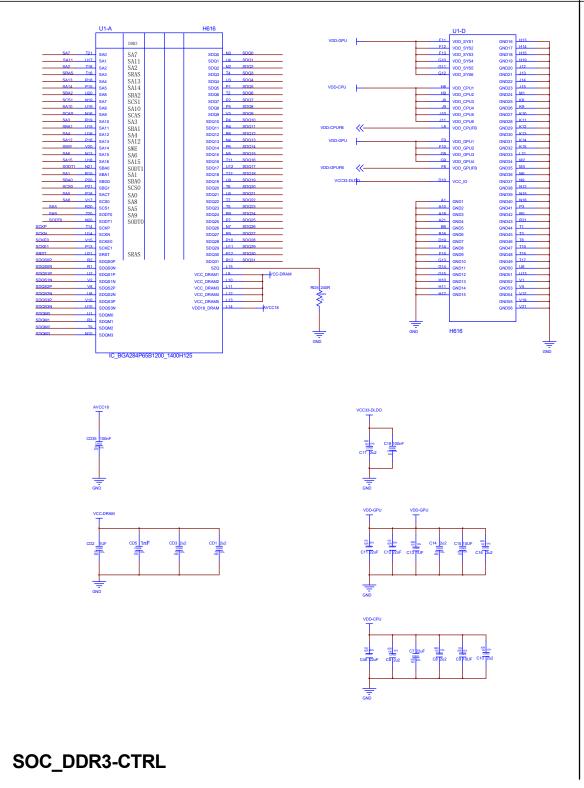


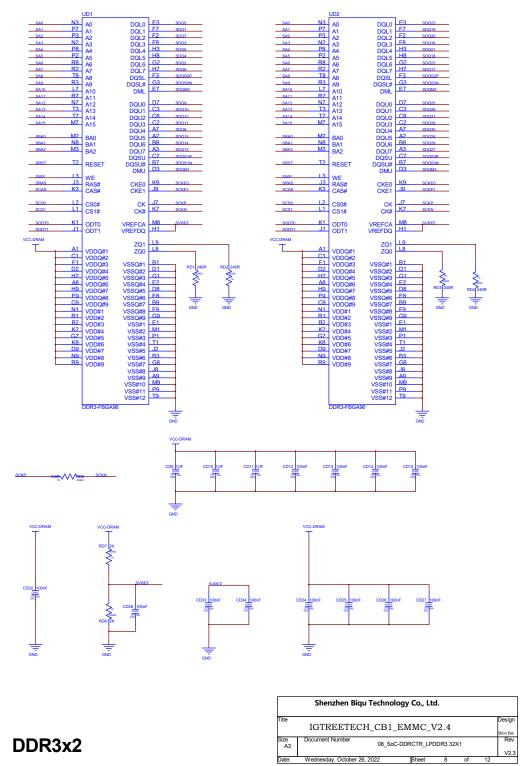


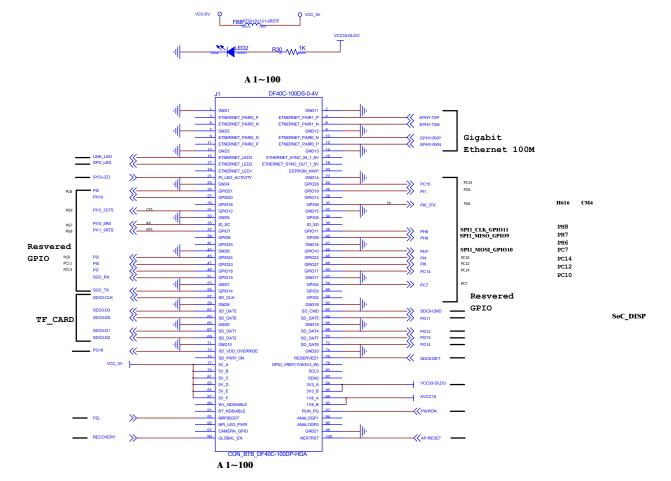




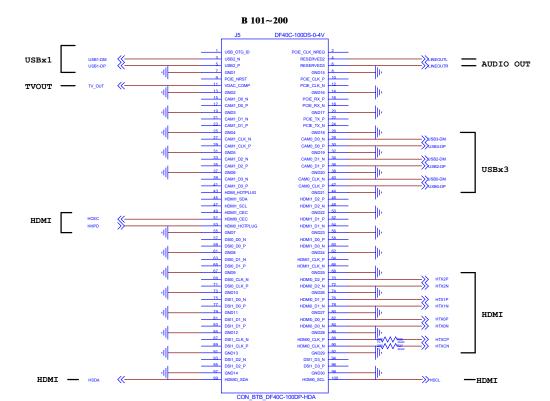
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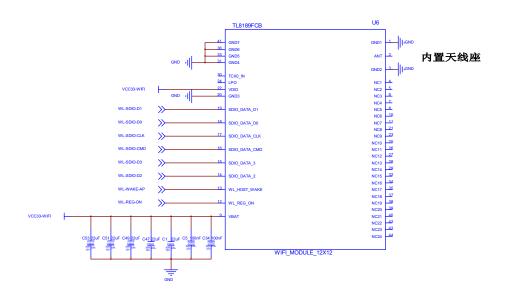


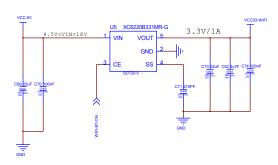
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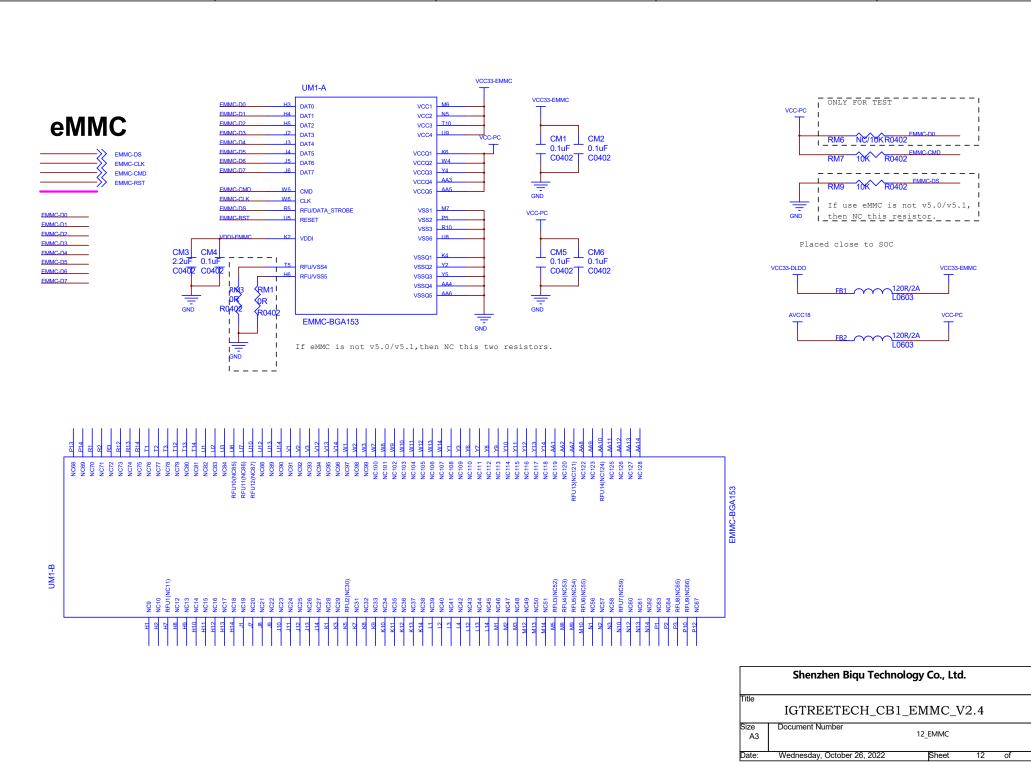
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TL8189FCB_MODULE

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